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S. Sohr, <i>Technical University Dresden</i> ; R. Rieske, <i>Technical University Dresden</i> ; K. Nieweglowski, <i>Technical University Dresden</i> ; K.-J. Wolter, <i>Technical University Dresden</i>	
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Shogo Ura, <i>Kyoto Institute of Technology</i> ; Kenji Kintaka, <i>AIST</i> ; Junichi Inoue, <i>Kyoto Institute of Technology</i> ; Tomonori Ogura, <i>Kyoto Institute of Technology</i> ; Kenzo Nishio, <i>Kyoto Institute of Technology</i> ; Yasuhiro Awatsuji, <i>Kyoto Institute of Technology</i>	
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H.H. Chang, <i>Industrial Technology Research Institute (ITRI)</i> ; C.H. Chien, <i>Industrial Technology Research Institute (ITRI)</i> ; H.C. Fu, <i>Industrial Technology Research Institute (ITRI)</i> ; W.L. Tsai, <i>Industrial Technology Research Institute (ITRI)</i> ; C.W. Chiang, <i>Industrial Technology Research Institute (ITRI)</i> ; C.T. Ko, <i>Industrial Technology Research Institute (ITRI)</i> ; Y.H. Chen, <i>Industrial Technology Research Institute (ITRI)</i> ; W.C. Lo, <i>Industrial Technology Research Institute (ITRI)</i> ; K.C. Su, <i>Brewer Science</i> ; C.S. Li, <i>Brewer Science</i>	
mmW Characterization of Wafer Level Passivation for 3D Silicon Interposer	1887
Y. Lamy, <i>CEA-LETI</i> ; O. El Bouayadi, <i>CEA-LETI</i> ; C. Ferrandon, <i>CEA-LETI</i> ; A. Schreiner, <i>CEA-LETI</i> ; T. Lacrevez, <i>IMEP-LAHC</i> ; C. Bermond, <i>IMEP-LAHC</i> ; A. Jouve, <i>CEA-LETI</i> ; S. Joblot, <i>STMicroelectronics</i> ; L. Dussopt, <i>CEA-LETI</i> ; B. Fléchet, <i>IMEP-LAHC</i>	

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Jason Luo, <i>University of California, Irvine</i> ; Edward Nelson, <i>University of California, Irvine</i> ; G.-P. Li, <i>University of California, Irvine</i> ; Mark Bachman, <i>University of California, Irvine</i>	
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Kyoung Youl Park, <i>Michigan State University</i> ; Nophadon Wiwatcharagoses, <i>Michigan State University</i> ; Premjeet Chahal, <i>Michigan State University</i>	
Advanced LED Package with Temperature Sensors and Microfluidic Cooling	1920
H. Ye, <i>Materials Innovation Institute (M2i), Delft University of Technology, Netherlands Organization for Applied Scientific Research (TNO)</i> ; H. van Zeijl, <i>Delft University of Technology</i> ; R. Sokolovskij, <i>Delft University of Technology</i> ; A.W.J. Gielen, <i>Netherlands Organization for Applied Scientific Research (TNO)</i> ; G.Q. Zhang, <i>Delft University of Technology</i>	
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Cheolbok Kim, <i>University of Florida</i> ; Jong Kyu Kim, <i>Electronics and Telecommunications Research Institute (ETRI)</i> ; Kyoung Tae Kim, <i>University of Florida</i> ; Yong-Kyu Yoon, <i>University of Florida</i>	
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Fei-Jain Wu, <i>Chipbond Technology Corporation</i> ; Lung-Hua Ho, <i>Chipbond Technology Corporation</i> ; Chih-Ming Kuo, <i>Chipbond Technology Corporation</i> ; Chia-Jung Tu, <i>Chipbond Technology Corporation</i> ; Chin-Tang Hsieh, <i>Chipbond Technology Corporation</i> ; Chih-Hsien Ni, <i>Chipbond Technology Corporation</i> ; Shih-Chieh Chang, <i>Chipbond Technology Corporation</i> ; Chuan-Yu Wu, <i>Chipbond Technology Corporation</i> ; Hui-Yu Huang, <i>Chipbond Technology Corporation</i> ; Kung-An Lin, <i>Chipbond Technology Corporation</i> ; You-Ming Hsu, <i>Chipbond Technology Corporation</i>	
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F. Altmann, <i>Fraunhofer IWM</i> ; S. Klengel, <i>Fraunhofer IWM</i> ; J. Schischka, <i>Fraunhofer IWM</i> ; M. Petzold, <i>Fraunhofer IWM</i>	
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Ningning Wang, <i>University College Cork</i> ; John Barry, <i>University College Cork</i> ; Jason Hannon, <i>University College Cork</i> ; Santosh Kulkarni, <i>University College Cork</i> ; Ray Foley, <i>United Technologies Research Centre</i> ; Kevin McCarthy, <i>University College Cork</i> ; Kenneth Rodgers, <i>University College Cork</i> ; Finbarr Waldron, <i>University College Cork</i> ; Mark Barry, <i>Tyndall National Institute</i> ; Declan Casey, <i>University College Cork</i> ; James Rohan, <i>University College Cork</i> ; Joe O'Brian, <i>University College Cork</i> ; Margaret Hegarty, <i>University College Cork</i> ; Ann-Marie Kelleher, <i>University College Cork</i> ; Saibal Roy, <i>University College Cork</i> ; Cian Ó Mathúna, <i>University College Cork</i>	
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Yiwei Wang, <i>University of Texas, Austin</i> ; Seung-Hyun Chae, <i>Texas Instruments, Inc.</i> ; Jay Im, <i>University of Texas, Austin</i> ; Paul S. Ho, <i>University of Texas, Austin</i>	

Laminates for Miniaturized Integrated Bioelectronic Protein Analysis Systems	1959
Sara Saedina, <i>University of California, Irvine</i> ; Kevin Limtao, <i>University of California, Irvine</i> ; Kent Nastiuk, <i>University of Rochester Medical Center</i> ; John Krolewski, <i>University of Rochester Medical Center</i> ; G.P. Li, <i>University of California, Irvine</i> ; Mark Bachman, <i>University of California, Irvine</i>	
A New 2.5D TSV Package Assembly Approach	1965
Yuan Lu, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Wen Yin, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Bo Zhang, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Daquan Yu, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Lixi Wan, <i>Chinese Academy of Sciences</i> ; Dongkai Shanguan, <i>National Center for Advanced Packaging, Chinese Academy of Sciences</i> ; Guofeng Xia, <i>Beijing University of Technology</i> ; Fei Qin, <i>Beijing University of Technology</i> ; Mao Ru, <i>Fudan University</i> ; Fei Xiao, <i>Fudan University</i>	
Fabrication and Characterization of Novel Photodefined Polymer-Enhanced Through-Silicon Vias for Silicon Interposers	1970
Paragkumar A. Thadesar, <i>Georgia Institute of Technology</i> ; Muhannad S. Bakir, <i>Georgia Institute of Technology</i>	
Process Characteristics of a 2.5D Silicon Module Using Embedded Technology as a Feasible Solution for System Integration and Thinner Form-Factor	1975
Ren-Shin Cheng, <i>Industrial Technology Research Institute (ITRI)</i> ; Yin-Po Hung, <i>Industrial Technology Research Institute (ITRI)</i> ; Tzu-Ying Kuo, <i>Industrial Technology Research Institute (ITRI)</i> ; Yu-Min Lin, <i>Industrial Technology Research Institute (ITRI)</i> ; Fan-Jun Leu, <i>Industrial Technology Research Institute (ITRI)</i> ; Tao-Chih Chang, <i>Industrial Technology Research Institute (ITRI)</i>	
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A Lumped/Discrete Port De-Embedding Method by Port Connection Error-Cancelling Network in Full-Wave Electromagnetic Modeling of 3D Integration and Packaging with Vertical Interconnects	1980
Zhaoqing Chen, <i>IBM Corporation</i>	
Current Density Effects on the Electrical Reliability of Ultra Fine-Pitch Micro-Bump for TSV Integration	1988
Young-Bae Park, <i>Andong National University</i> ; Seung-Hyun Kim, <i>Andong National University</i> ; Jong-Jin Park, <i>Andong National University</i> ; June-Bum Kim, <i>Andong National University</i> ; Ho-Young Son, <i>SK Hynix Inc.</i> ; Kwon-Whan Han, <i>SK Hynix Inc.</i> ; Jae-Sung Oh, <i>SK Hynix Inc.</i> ; Nam-Seog Kim, <i>SK Hynix Inc.</i> ; Sehoon Yoo, <i>Korean Institute of Industrial Technology</i>	
Fixture-Free Measurement Technique for PDN Discrete Components	1994
Di Hu, <i>Qualcomm Technologies, Inc.</i> ; Jaemin Shin, <i>Qualcomm Technologies, Inc.</i> ; Timothy Michalka, <i>Qualcomm Technologies, Inc.</i>	
High-Performance RF Components Using Capacitively-Coupled Contacts over III-N Heterostructures	2002
F. Jahan, <i>University of South Carolina</i> ; Y.-H. Yang, <i>University of South Carolina</i> ; M. Gaevski, <i>Sensor Electronic Technology, Inc.</i> ; J. Deng, <i>Sensor Electronic Technology, Inc.</i> ; R. Gaska, <i>Sensor Electronic Technology, Inc.</i> ; M. Shur, <i>Rensselaer Polytechnic Institute</i> ; G. Simin, <i>University of South Carolina</i>	
High-Frequency (RF) Electrical Analysis of Through Silicon Via (TSV) for Different Designed TSV Patterns	2006
Hsin-Kai Huang, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chun-Hsun Lin, <i>Siliconware Precision Industries Co., Ltd.</i> ; Chris Liu, <i>Siliconware Precision Industries Co., Ltd.</i> ; Kwan-Chin Fan, <i>Siliconware Precision Industries Co., Ltd.</i> ; Hsin-Hung Lee, <i>Siliconware Precision Industries Co., Ltd.</i>	

Fast Signal Integrity Methodology for PCB Pre-Layout Analysis and Layout Quality Check	2012
Jimmy Hsu, <i>Intel Corporation</i> ; Thonas Su, <i>Intel Corporation</i> ; Yuan-Liang Li, <i>Intel Corporation</i> ; Edward Hsiung, <i>Intel Corporation</i> ; Kai Xiao, <i>Intel Corporation</i> ; Xiaoning Ye, <i>Intel Corporation</i> ; Kai-Bin Wu, <i>Intel Corporation</i>	
3D Antenna for GHz Application and Vibration Energy Harvesting	2018
Konstantin Kholostov, <i>University of Rome</i> ; Paolo Nenzi, <i>University of Rome</i> ; Fabrizio Palma, <i>University of Rome</i> ; Marco Balucani, <i>University of Rome</i>	
Electrical Performance Modeling of Unbalanced Comb Tree Networks on Advanced PCB Interconnects for High-Rate Clock Signal Distribution	2024
Thomas Eudes, <i>ESIGELEC</i> ; Blaise Ravelo, <i>ESIGELEC</i> ; Thierry Lacrevez, <i>Université de Savoie</i> ; Bernard Fléchet, <i>Université de Savoie</i>	
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Zhaoli Gao, <i>Chalmers University of Technology, Hong Kong University of Science and Technology</i> ; Yong Zhang, <i>Chalmers University of Technology, Shanghai University</i> ; Yifeng Fu, <i>SHT Smart High Tech AB</i> ; Matthew Yuen, <i>Hong Kong University of Science & Technology (HKUST)</i> ; Johan Liu, <i>Chalmers University of Technology, Shanghai University</i>	
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